



SOT1254

Plastic thermal enhanced small outline package (DFN56 AD);
8 Leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DPAK
Package type industry code	DFN56 AD
Package style descriptive code	HSO (thermal enhanced small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-11-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.9	-	6	6.1	mm
E	package width		4.9	-	5	5.1	mm
A	seated height		0.85	-	0.9	0.95	mm
e	nominal pitch		-	-	1.27	-	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline

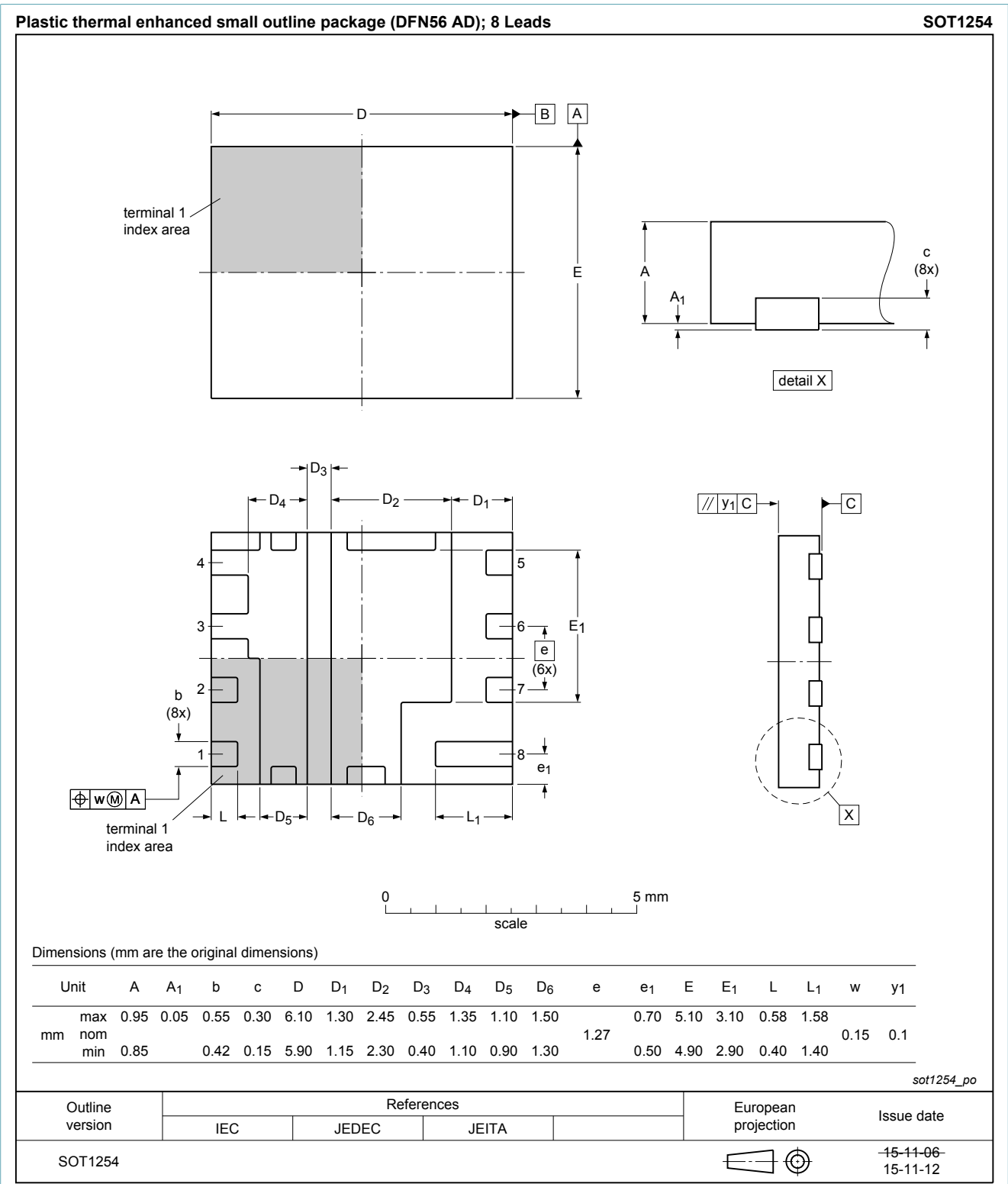


Fig. 1. Package outline DFN56 AD (SOT1254)

3. Legal information

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